Qualcom

RF360 Europe GmbH

Data sheet

SAW duplexer

Series/type:	B8674
Ordering code:	B39272B8674P810
Date:	November 19, 2018
Version:	2.5

DCN: 80-PA243-56 Rev. A

RF360 products mentioned within this document are products of RF360 Europe GmbH and other subsidiaries of RF360 Holdings Singapore Pte. Ltd. (collectively, the "RF360 Subsidiaries").

RF360 Europe GmbH, Anzinger Str. 13, München, Germany © 2019 RF360 Europe GmbH and/or its affiliated companies. All rights reserved.



These materials, including the information contained herein, may be used only for informational purposes by the customer. The RF360 Subsidiaries assume no responsibility for errors or omissions in these materials or the information contained herein. The RF360 Subsidiaries reserve the right to make changes to the product(s) or information contained herein without notice. The materials and information are provided on an AS IS basis, and the RF360 Subsidiaries assume no liability and make no warranty or representation, either expressed or implied, with respect to the materials, or any output or results based on the use, application, or evaluation of such materials, including, without limitation, with respect to the non-infringement of trademarks, patents, copyrights or any other intellectual property rights or other rights of third parties.

No use of this documentation or any information contained herein grants any license, whether express, implied, by estoppel or otherwise, to any intellectual property rights, including, without limitation, to any patents owned by QUALCOMM Incorporated or any of its subsidiaries.

Not to be used, copied, reproduced, or modified in whole or in part, nor its contents revealed in any manner to others without the express written permission of RF360 Europe GmbH.

Qualcomm is a trademark of Qualcomm Incorporated, registered in the United States and other countries. Other product and brand names may be trademarks or registered trademarks of their respective owners.

This technical data may be subject to U.S. and international export, re-export, or transfer ("export") laws. Diversion contrary to U.S. and international law is strictly prohibited.



RF360 Europe GmbH A Qualcomm – TDK Joint Venture

Data sheet

SAW duplexer

Series/type:	B8674
Ordering code:	B39272B8674P810
Date:	November 19, 2018
Version:	2.5

DCN: 80-PA243-56 Rev. A

RF360 products mentioned within this document are products of RF360 Europe GmbH and other subsidiaries of RF360 Holdings Singapore Pte. Ltd. (collectively, the "RF360 Subsidiaries").

RF360 Holdings Singapore Pte. Ltd. is a joint venture of Qualcomm Global Trading Pte. Ltd. and EPCOS AG.

RF360 Europe GmbH, Anzinger Str. 13, München, Germany

© 2018 RF360 Europe GmbH and/or its affiliated companies. All rights reserved.



SAW duplexer B8674 Data sheet

These materials, including the information contained herein, may be used only for informational purposes by the customer. The RF360 Subsidiaries assume no responsibility for errors or omissions in these materials or the information contained herein. The RF360 Subsidiaries reserve the right to make changes to the product(s) or information contained herein without notice. The materials and information are provided on an AS IS basis, and the RF360 Subsidiaries assume no liability and make no warranty or representation, either expressed or implied, with respect to the materials, or any output or results based on the use, application, or evaluation of such materials, including, without limitation, with respect to the non-infringement of trademarks, patents, copyrights or any other intellectual property rights or other rights of third parties.

No use of this documentation or any information contained herein grants any license, whether express, implied, by estoppel or otherwise, to any intellectual property rights, including, without limitation, to any patents owned by QUALCOMM Incorporated or any of its subsidiaries.

Not to be used, copied, reproduced, or modified in whole or in part, nor its contents revealed in any manner to others without the express written permission of RF360 Europe GmbH.

Qualcomm is a trademark of Qualcomm Incorporated, registered in the United States and other countries. Other product and brand names may be trademarks or registered trademarks of their respective owners.

This technical data may be subject to U.S. and international export, re-export, or transfer ("export") laws. Diversion contrary to U.S. and international law is strictly prohibited.

Table of contents

1 Application	4
2 Features	
3 Package	
4 <u>Pin configuration</u>	
5 <u>Matching circuit</u>	
6 <u>Characteristics</u> .	
7 Maximum ratings	
8 Transmission coefficients	
9 <u>Reflection coefficients</u>	
10 EVMs	17
11 Packing material	
12 Marking	
13 <u>Soldering profile</u>	
14 Annotations	
15 <u>Cautions and warnings</u>	
16 Important notes	

1 Application

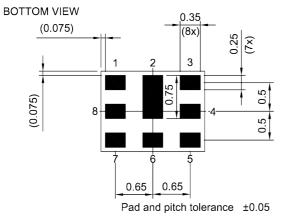
- Low-loss SAW duplexer for mobile telephone LTE Band 7 systems.
- Low insertion attenuation
- Low amplitude ripple
- Usable pass band 70 MHz
- 50 Ω single-ended in both in Antenna-Rx and Tx-Antenna paths.

2 Features

- Package size 1.8±0.1 mm × 1.4±0.1 mm
- Package height 0.475 mm (max.)
- Approximate weight 4 mg
- RoHS compatible
- Package for Surface Mount Technology (SMT)
- Ni/Au-plated terminals
- Electrostatic Sensitive Device (ESD)
- Moisture Sensitivity Level 3 (MSL3)

Qualconversion RF360 Europe GmbH A Qualcomm – TDK Joint Venture

3 Package



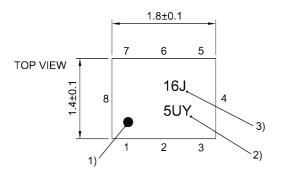
4 Pin configuration



■ 2, 4, 5, 7, 8 Ground

SIDE VIEW





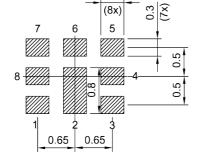
1) Marking for pad number 1

2) Example of encoded lot number

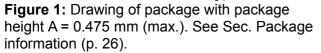
0.4

3) Example of encoded filter type number

Land pattern THRU VIEW



Landing pad tolerance -0.02





5 Matching circuit

■ *L*_{p6} = 2.7 nH

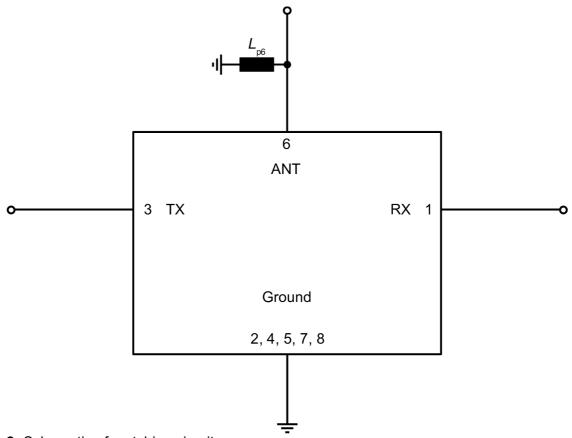


Figure 2: Schematic of matching circuit.

External shunt inductor for ESD protection is recommended at any ports towards antenna.

RF360 Europe GmbH A Qualcomm – TDK Joint Venture

6 Characteristics

Qualcom

6.1 TX – ANT

Temperature range for specification	$T_{_{\rm SPEC}}$	= −30 °C +85 °C
TX terminating impedance	Z _{TX}	= 50 Ω
ANT terminating impedance	Z	= 50 Ω with par. 2.7 nH ¹⁾
RX terminating impedance	Z _{RX}	= 50 Ω

Characteristics TX – ANT				min. for $T_{_{\rm SPEC}}$	typ. @ +25 °C	max. for $T_{\rm SPEC}$	
Center frequency			f _c	—	2535	—	MHz
Maximum insertion attenuation			$\alpha_{_{max}}$				
	2500 2570	MHz		—	1.8	2.7	dB
Amplitude ripple (p-p)			Δα				
	2500 2570	MHz		—	0.8	1.7	dB
Maximum VSWR			$VSWR_{max}$				
@ TX port	2500 2570	MHz		—	1.6	2.0	
@ ANT port	2500 2570	MHz		_	1.6	2.0	
Maximum error vector magnitude			EVM _{max} ²⁾				
	2502.4 2567.6	MHz		—	0.6	2.0	%
Minimum attenuation							
	10 1559	MHz	$\alpha_{_{min}}$	35	40		dB
	1559 1563	MHz	$\alpha_{_{min}}$	35	40		dB
	1565.42 1573.37		$\alpha_{_{min}}$	35	40	—	dB
	1573.374 1577.46	6 MHz	$\alpha_{_{min}}$	35	40		dB
	1577.466 1585.42	2 MHz	$\alpha_{_{min}}$	35	40	—	dB
	1597.552 1605.88	86 MHz	$\alpha_{_{min}}$	35	40	—	dB
	1605.886 1680	MHz	$\alpha_{_{min}}$	35	39	_	dB
	1805 1880	MHz	$\alpha_{_{min}}$	35	39	—	dB
	1900 1920	MHz	$\alpha_{_{min}}$	35	39	—	dB
	2010 2025	MHz	$\alpha_{_{min}}$	35	39	_	dB
	2110 2170	MHz	$\alpha_{_{min}}$	35	39	—	dB
	2402 2440	MHz	$\alpha_{_{min}}$	45	52	—	dB
Ch 1	2403 2421	MHz	$lpha_{_{WLAN,min}}^{3)}$	54 ⁴⁾	56	—	dB
Ch 2	2408 2426	MHz	α ³⁾ WLAN,min	53 ⁴⁾	55		dB
Ch 3	2413 2431	MHz	α ³⁾ WLAN,min	52 ⁴⁾	54		dB
Ch 4	2418 2436	MHz	α ³⁾ WLAN,min	52 ⁴⁾	54	_	dB
Ch 5	2423 2441	MHz	WLAN,min $(\alpha_{WLAN,min}^{3)}$	52 ⁴⁾	54	_	dB
Ch 6	2428 2446	MHz	WLAN,min $(\alpha_{WLAN,min}^{3)}$	52 ⁴⁾	54	_	dB
Ch 7	2433 2451	MHz	WLAN,min $\alpha_{_{WLAN,min}}^{3)}$	52 ⁴⁾	55	_	dB
Ch 8	2438 2456	MHz		52 ⁴⁾	56	_	dB
	2440 2460	MHz	α ³⁾ _{WLAN,min}	40	47		dB
		111112	$\alpha_{_{min}}$		1		

Page 7 of 27

Qualcomm

RF360 Europe GmbH A Qualcomm – TDK Joint Venture

Characteristics TX – ANT				min. for $T_{\rm SPEC}$	typ. @ +25 °C	max. for $T_{\rm SPEC}$	
Ch 9	2443 2461	MHz	$lpha_{_{WLAN,min}}^{_{3)}}$	49 ⁴⁾	53	—	dB
Ch 10	2448 2466	MHz	$\alpha_{_{WLAN,min}}^{\qquad 3)}$	46 ⁴⁾	49	—	dB
Ch 11	2453 2471	MHz	$\alpha_{_{WLAN,min}}^{\qquad 3)}$	44 ⁴⁾	47	—	dB
Ch 12	2458 2476	MHz	$\alpha_{_{WLAN,min}}^{\qquad 3)}$	35 ⁴⁾	43	—	dB
Ch 13	2463 2481	MHz	$\alpha_{_{WLAN,min}}^{\qquad 3)}$	21 ⁴⁾	30	_	dB
	2470 2474	MHz	$\alpha_{_{min}}$	16	41	_	dB
	2474 2500	MHz	$\alpha_{_{min}}$	0.5	1.7	_	dB
	2590 2620	MHz	$\alpha_{_{min}}$		4	_	dB
	2620 2690	MHz	$\alpha_{_{min}}$	45	52	_	dB
	3300 3800	MHz	$\alpha_{_{min}}$	39	44	_	dB
	4900 5000	MHz	$\alpha_{_{min}}$	44	49	_	dB
	5000 5140	MHz	$\alpha_{_{min}}$	44	48	_	dB
	5140 5280	MHz	$\alpha_{_{min}}$	44	48	_	dB
	7500 7710	MHz	$\alpha_{_{min}}$		30	—	dB

1)

See Sec. Matching circuit (p. 6). Error Vector Magnitude (EVM) based on definition in 3GPP TS 25.141. 2)

3) Average over each WLAN channel with band width of 18 MHz.

4) Valid for typical temperature T = +25 °C.

6.2 ANT – RX

Temperature range for specification	T _{SPEC}	= −30 °C +85 °C
TX terminating impedance	Z _{TX}	= 50 Ω
ANT terminating impedance	Z	= 50 Ω with par. 2.7 nH ¹⁾
RX terminating impedance	Z _{RX}	= 50 Ω

Characteristics ANT – RX				min. for $T_{\rm SPEC}$	typ. @ +25 °C	max. for $T_{_{\rm SPEC}}$	
Center frequency			f _c		2655		MHz
Maximum insertion attenuation			$\alpha_{_{max}}$				
	2620 2690	MHz		—	1.9	2.9	dB
Amplitude ripple (p-p)			Δα				
	2620 2690	MHz		_	0.6	1.6	dB
Maximum VSWR			VSWR _{max}				
@ ANT port	2620 2690	MHz		_	1.6	2.0	
@ RX port	2620 2690	MHz		_	1.6	2.0	
Maximum error vector magnitude			EVM _{max} ²⁾				
	2622.4 2687.6	MHz		_	0.8	2.0	%
Minimum attenuation			$\alpha_{_{min}}$				
	10 718	MHz		50	56	_	dB
	45	MHz		50	90	_	dB
	718 748	MHz		50	56	_	dB
	814 849	MHz		47	54	—	dB
	832 862	MHz		47	54	—	dB
	880 915	MHz		47	53	—	dB
	1710 1785	MHz		38	43	—	dB
	1920 1980	MHz		37	42	—	dB
	2400 2500	MHz		40	45	—	dB
	2500 2570	MHz		45	55	—	dB
	2570 2600	MHz		3	7	—	dB
	2775 2790	MHz		40	55	—	dB
	2790 2810	MHz		40	55		dB
	2810 3660	MHz		39	44	—	dB
	3600 4900	MHz		39	44		dB
	4900 5300	MHz		35	43	—	dB
	5300 5950	MHz		32	39	—	dB
	7620 7830	MHz		15	22	—	dB

1)

See Sec. Matching circuit (p. 6). Error Vector Magnitude (EVM) based on definition in 3GPP TS 25.141. 2)

6.3 TX – RX

Temperature range for specification	$T_{_{\rm SPEC}}$	= −30 °C +85 °C
TX terminating impedance	Z _{TX}	= 50 Ω
ANT terminating impedance	Z	= 50 Ω with par. 2.7 nH ¹⁾
RX terminating impedance	Z _{RX}	= 50 Ω

Characteristics TX – RX				min. for $T_{\rm SPEC}$	typ. @ +25 °C	$\begin{array}{c} \text{max.} \\ \text{for } \mathcal{T}_{_{\text{SPEC}}} \end{array}$	
Minimum isolation			$\alpha_{_{min}}$				
	1574 1577	MHz		30	65	—	dB
	2500 2570	MHz		53	56	_	dB
	2620 2690	MHz		50	54	_	dB
	5000 5140	MHz		30	51	_	dB
	7500 7710	MHz		25	44	_	dB

¹⁾ See Sec. Matching circuit (p. 6).

6.4 Linearity

Temperature range for specification	$T_{_{\rm SPEC}}$	= −30 °C +85 °C
TX terminating impedance	Z _{TX}	= 50 Ω
ANT terminating impedance	Z	= 50 Ω with par. 2.7 nH ¹⁾
RX terminating impedance	Z _{RX}	= 50 Ω

Characteristics			min. for T_{SPEC}	typ. @ +25 °C	max. for T_{SPEC}	
IMD product levels						
IMD2 ²⁾						
Blocker 1	120	MHz	_	-136	-110	dBm
Blocker 3	5190	MHz	_	-110	-100	dBm
IMD3 ²⁾						
Blocker 2	2415	MHz	—	-105	-100	dBm

1)

See Sec. Matching circuit (p. 6). IMD product level limits for power levels P_{TX} = 21.5 dBm (antenna port output power) and $P_{blocker}$ = -15 dBm (antenna 2) port input power).

7 Maximum ratings

Storage temperature	$T_{\rm STG}^{1)} = -40 ^{\circ}{\rm C} \dots +85 ^{\circ}{\rm C}$	
DC voltage	$ V_{\rm DC} = 5.0 \rm V (max.)^{2}$	
ESD voltage		
	$V_{\rm ESD}^{3)} = 50 \rm V (max.)$	Machine model.
	$V_{\rm ESD}^{4)}$ = 100+ V (max.)	Human body model.
	V _{ESD} ⁵⁾ = 100+ V (max.)	Charged device model.
Input power	P _{IN}	
@ TX port: 2500 2570 MHz	29 dBm	Continuous wave for 5000 h @ 50 °C.
@ TX port: other frequency ranges	10 dBm	Continuous wave for 5000 h @ 50 °C.

¹⁾ Not valid for packaging material. Storage temperature for packaging material is -25 °C to +40 °C.

²⁾ 168h Damp Heat Steady State acc. IEC 60068-2-67 Cy.

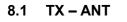
³⁾ According to JESD22-A115B (MM – Machine Model), 10 negative & 10 positive pulses.

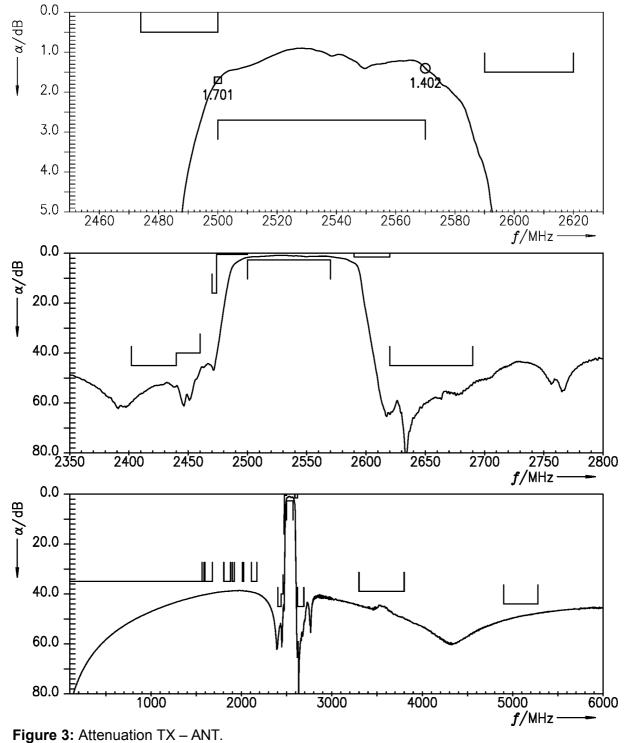
⁴⁾ According to JESD22-A114F (HBM – Human Body Model), 1 negative & 1 positive pulse.

⁵⁾ According to JESD22-C101C (CDM – Field Induced Charged Device Model), 3 negative & 3 positive pulses.

Qualconversion RF360 Europe GmbH A Qualcomm – TDK Joint Venture

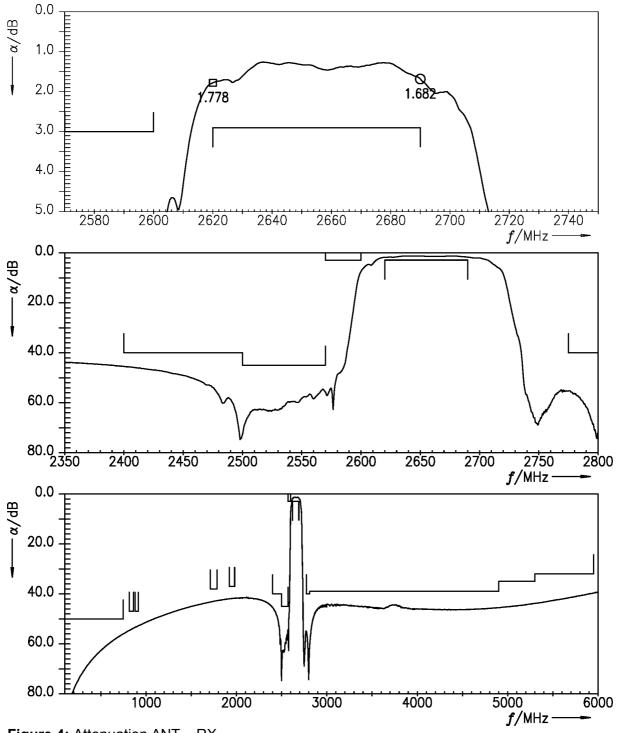
8 Transmission coefficients

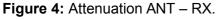




Qualcomm RF360 Europe GmbH A Qualcomm – TDK Joint Venture

8.2 ANT – RX

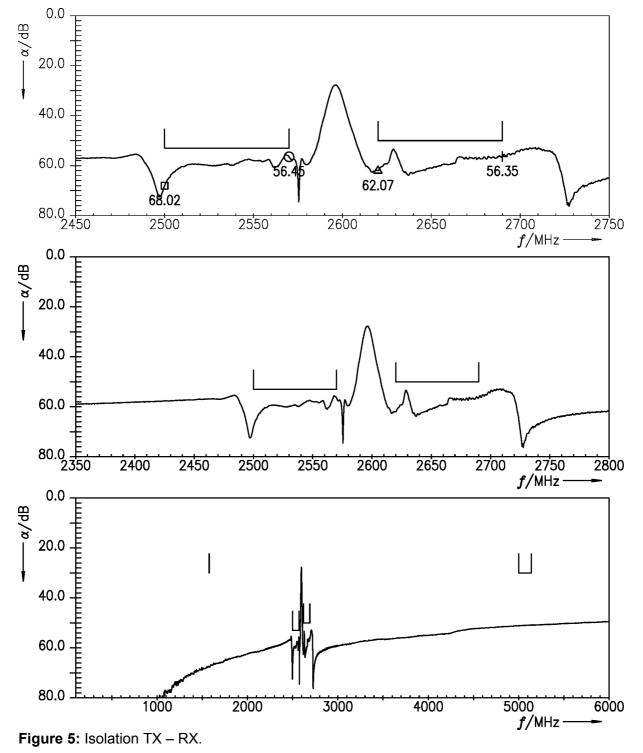




Please read **Cautions and warnings** and **Important notes** at the end of this document.

Qualcomm RF360 Europe GmbH A Qualcomm – TDK Joint Venture

8.3 TX – RX



RF360 Europe GmbH A Qualcomm – TDK Joint Venture

□ = 2500.0 O = 2570.0

9 Reflection coefficients

Qualcom

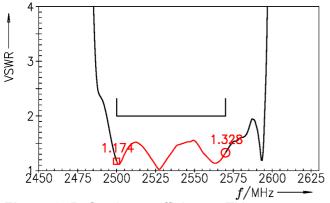


Figure 6: Reflection coefficient at TX port.

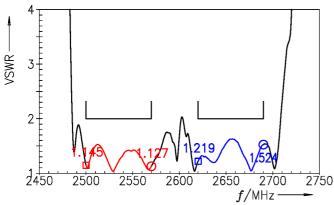
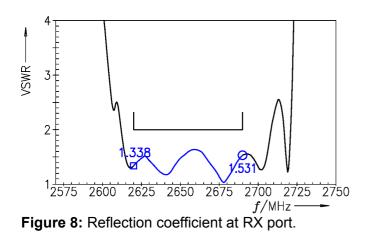
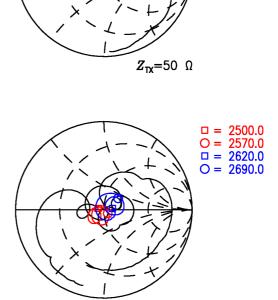
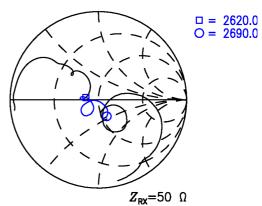


Figure 7: Reflection coefficient at ANT port.





 $Z_{ANT} = 50 \Omega$





10 EVMs

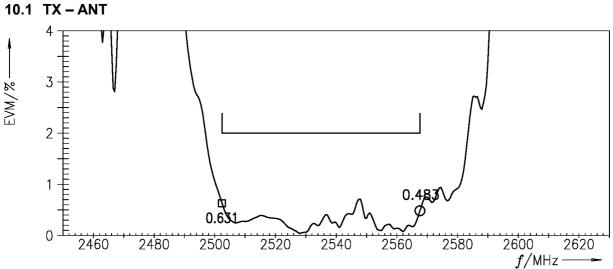


Figure 9: Error vector magnitude TX – ANT.



10.2 ANT – RX

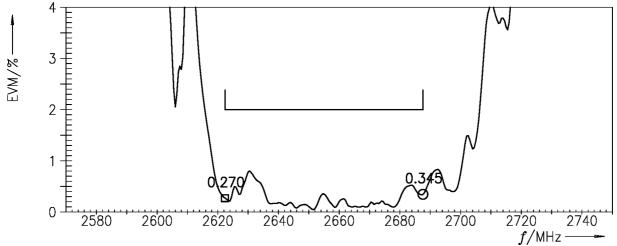
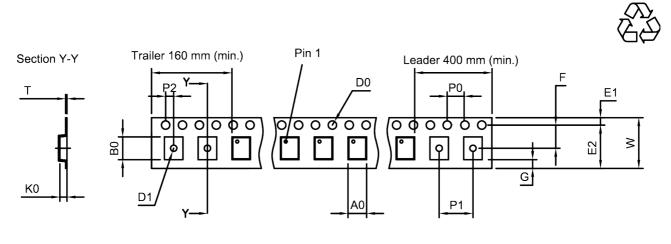


Figure 10: Error vector magnitude ANT – RX.



11 Packing material

11.1 Tape



User direction of unreeling

Figure 11: Drawing of tape (first-angle projection) for illustration only and not to scale. The valid tape dimensions are listed in Table 1.

A ₀	1.6±0.05 mm
B ₀	2.0±0.05 mm
D ₀	1.5 +0.1/-0 mm
D ₁	0.8+0.1/-0 mm
E1	1.75±0.1 mm

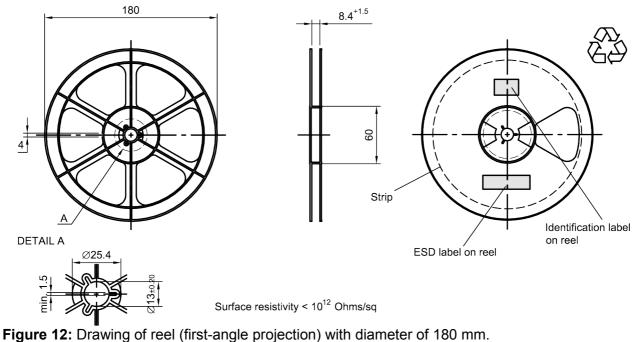
E ₂	6.25 mm (min.)
F	3.5±0.05 mm
G	0.75 mm (min.)
K ₀	0.64±0.05 mm
P ₀	4.0±0.1 mm

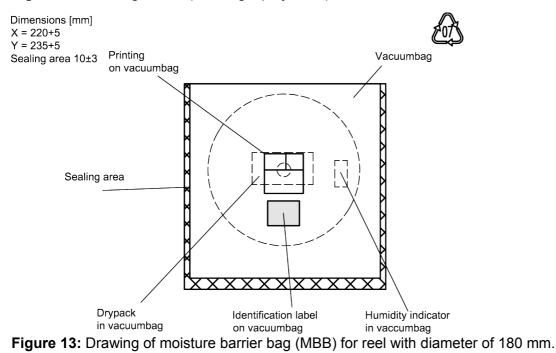
P ₁	4.0±0.1 mm
P ₂	2.0±0.05 mm
Т	0.25±0.03 mm
W	8.0+0.3/-0.1 mm

Table 1: Tape dimensions.



11.2 Reel with diameter of 180 mm





Qualcomm RF360 Europe GmbH A Qualcomm – TDK Joint Venture

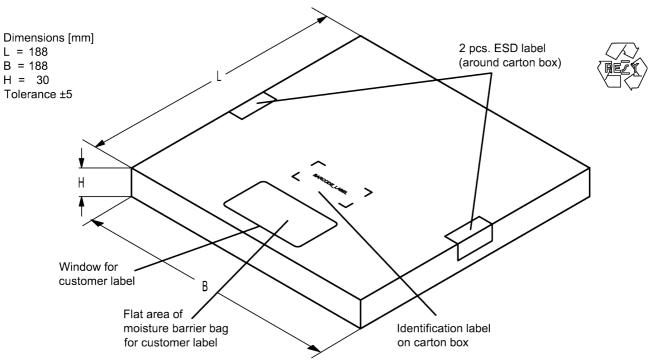


Figure 14: Drawing of folding box for reel with diameter of 180 mm.

11.3 Reel with diameter of 330 mm

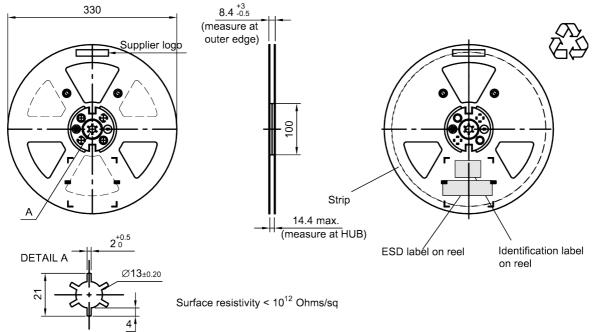


Figure 15: Drawing of reel (first-angle projection) with diameter of 330 mm.



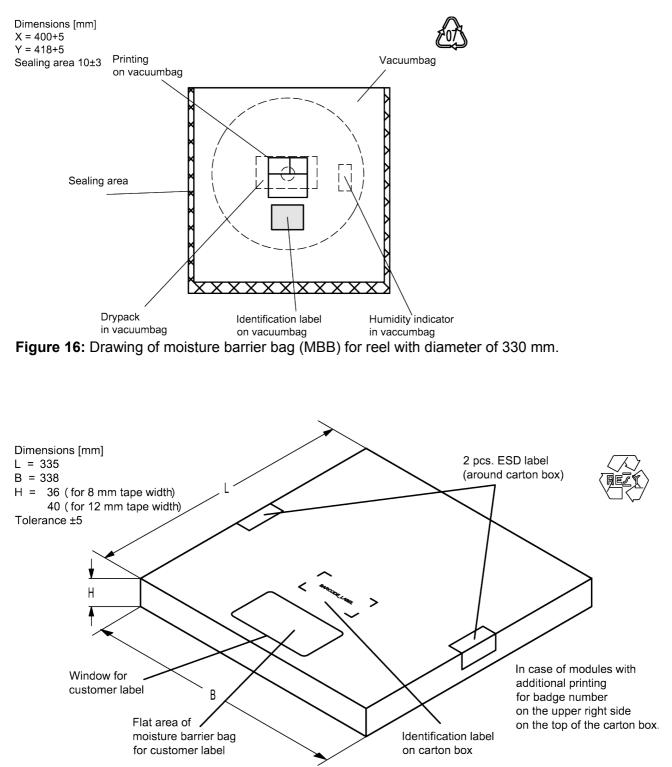


Figure 17: Drawing of folding box for reel with diameter of 330 mm.

12 Marking

Products are marked with product type number and lot number encoded according to Table 2:

■ Type number:

The 4 digit type number is encoded by a special	of the ordering code, BASE32 code into a 3 digit marking.	e.g., B3xxxxB <u>1234</u> xxxx,
Example of decoding 16J	type number marking on device =>	in decimal code. 1234
	32 ¹ + 18 (=J) x 32 ⁰ = oduct type B8674 is 8F2.	1234

■ Lot number:

The last 5 digits of the lot number, 12345, e.g., are encoded based on a special BASE47 code into a 3 digit marking.

Example of decoding lot number marking on device **5UY**

decoding lot number marking on device		in decimal code.
5UY	=>	12345
5 x 47 ² + 27 (=U) x 47 ¹ + 31 (=Y) x 47 ⁰	=	12345

Adopted BASE32 code for type number			
Decimal	Base32	Decimal	Base32
value	code	value	code
0	0	16	G
1	1	17	Н
2	2	18	J
3	3	19	K
4	4	20	М
5	5	21	N
6	6	22	Р
7	7	23	Q
8	8	24	R
9	9	25	S
10	А	26	Т
11	В	27	V
12	С	28	W
13	D	29	Х
14	E	30	Y
15	F	31	Z

Adopted BASE47 code for lot number			
Decimal	Base47	Decimal	Base47
value	code	value	code
0	0	24	R
1	1	25	S
2	2	26	Т
3	3	27	U
4	4	28	V
5	5	29	W
6	6	30	Х
7	7	31	Y
8	8	32	Z
9	9	33	b
10	Α	34	d
11	В	35	f
12	С	36	h
13	D	37	n
14	E	38	r
15	F	39	t
16	G	40	v
17	Н	41	١
18	J	42	?
19	К	43	{
20	L	44	}
21	М	45	<
22	N	46	>
23	Р		

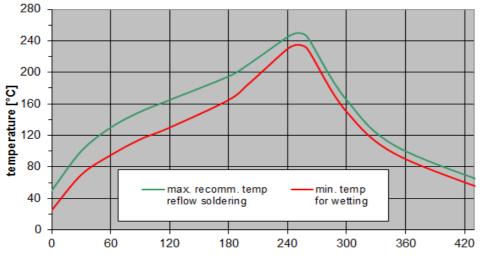
Table 2: Lists for encoding and decoding of marking.

13 Soldering profile

The recommended soldering process is in accordance with IEC 60068-2-58 – 3rd edit and IPC/JEDEC J-STD-020B.

ramp rate	≤ 3 K/s
preheat	125 °C to 220 °C, 150 s to 210 s, 0.4 K/s to 1.0 K/s
<i>T</i> > 220 °C	30 s to 70 s
<i>T</i> > 230 °C	min. 10 s
<i>T</i> > 245 °C	max. 20 s
<i>T</i> ≥ 255 °C	_
peak temperature T_{peak}	250 °C +0/-5 °C
wetting temperature T_{min}	230 °C +5/-0 °C for 10 s ± 1 s
cooling rate	≤ 3 K/s
soldering temperature T	measured at solder pads

 Table 3: Characteristics of recommended soldering profile for lead-free solder (Sn95.5Ag3.8Cu0.7).



time [s]

Figure 18: Recommended reflow profile for convection and infrared soldering – lead-free solder.

14 Annotations

14.1 RoHS compatibility

ROHS-compatible means that products are compatible with the requirements according to Art. 4 (substance restrictions) of Directive 2011/65/EU of the European Parliament and of the Council of June 8th, 2011, on the restriction of the use of certain hazardous substances in electrical and electronic equipment ("Directive") with due regard to the application of exemptions as per Annex III of the Directive in certain cases.

14.2 Scattering parameters (S-parameters)

The pin/port assignment is available in the headers of the S-parameter files. Please contact your local RF360 sales office.

14.3 Ordering codes and packing units

Ordering code	Packing unit
B39272B8674P810	15000 pcs
B39272B8674P810S 5	5000 pcs

Table 4: Ordering codes and packing units.

15 Cautions and warnings

15.1 Display of ordering codes for RF360 products

The ordering code for one and the same product can be represented differently in data sheets, data books, other publications and the website of RF360, or in order-related documents such as shipping notes, order confirmations and product labels. The varying representations of the ordering codes are due to different processes employed and do not affect the specifications of the respective products. Detailed information can be found on the Internet under <u>www.rf360jv.com/orderingcodes</u>.

15.2 Material information

Due to technical requirements components may contain dangerous substances. For information on the type in question please also contact one of our sales offices.

For information on recycling of tapes and reels please contact one of our sales offices.

15.3 Moldability

Before using in overmolding environment, please contact your local RF360 sales office.

15.4 Package information

Landing area

The printed circuit board (PCB) land pattern (landing area) shown is based on RF360 internal development and empirical data and illustrated for example purposes, only. As customers' SMD assembly processes may have a plenty of variants and influence factors which are not under control or knowledge of RF360, additional careful process development on customer side is necessary and strongly recommended in order to achieve best soldering results tailored to the particular customer needs.

Dimensions

Unless otherwise specified all dimensions are understood using unit millimeter (mm).

Projection method

Unless otherwise specified first-angle projection is applied.

16 Important notes

The following applies to all products named in this publication:

- 1. Some parts of this publication contain statements about the suitability of our products for certain areas of application. These statements are based on our knowledge of typical requirements that are often placed on our products in the areas of application concerned. We nevertheless expressly point out that such statements cannot be regarded as binding statements about the suitability of our products for a particular customer application. As a rule, RF360 Europe GmbH and its affiliates are either unfamiliar with individual customer applications or less familiar with them than the customers themselves. For these reasons, it is always ultimately incumbent on the customer to check and decide whether an RF360 product with the properties described in the product specification is suitable for use in a particular customer application.
- 2. We also point out that in individual cases, a malfunction of electronic components or failure before the end of their usual service life cannot be completely ruled out in the current state of the art, even if they are operated as specified. In customer applications requiring a very high level of operational safety and especially in customer applications in which the malfunction or failure of an electronic component could endanger human life or health (e.g. in accident prevention or life-saving systems), it must therefore be ensured by means of suitable design of the customer application or other action taken by the customer (e.g. installation of protective circuitry or redundancy) that no injury or damage is sustained by third parties in the event of malfunction or failure of an electronic component.
- 3. The warnings, cautions and product-specific notes must be observed.
- 4. In order to satisfy certain technical requirements, some of the products described in this publication may contain substances subject to restrictions in certain jurisdictions (e.g. because they are classed as hazardous). Useful information on this will be found in our Material Data Sheets on the Internet (www.rf360jv.com/material). Should you have any more detailed questions, please contact our sales offices.
- 5. We constantly strive to improve our products. Consequently, the products described in this publication may change from time to time. The same is true of the corresponding product specifications. Please check therefore to what extent product descriptions and specifications contained in this publication are still applicable before or when you place an order. We also reserve the right to discontinue production and delivery of products. Consequently, we cannot guarantee that all products named in this publication will always be available.

The aforementioned does not apply in the case of individual agreements deviating from the foregoing for customer-specific products.



单击下面可查看定价,库存,交付和生命周期等信息

>>RF360 / Qualcomm